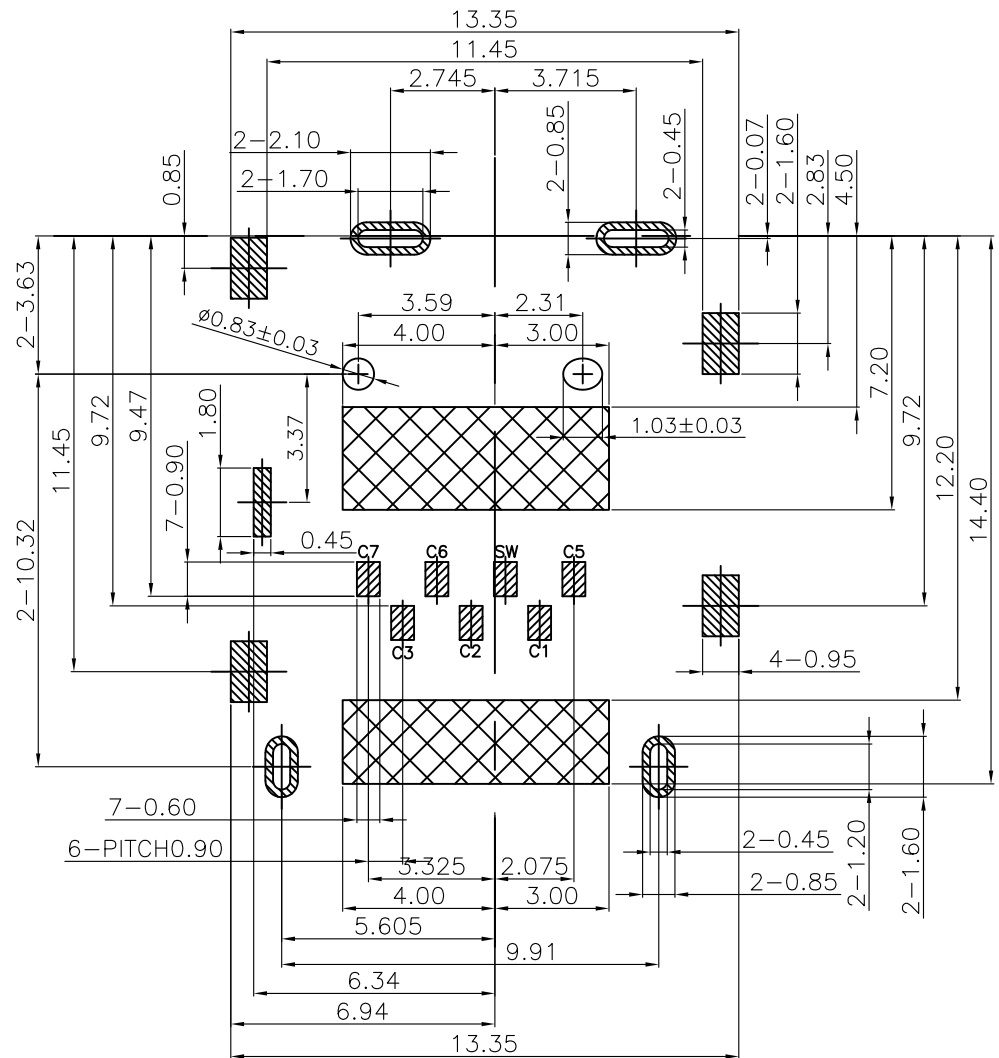


PART.NO.:
SP135-AN401-**

- 08: 功能区镀金1U", 锡脚Gold Flash
- 09: 功能区镀金3U", 锡脚Gold Flash
- 10: 功能区镀金5U", 锡脚Gold Flash
- 11: 功能区镀金15U", 锡脚Gold Flash
- 12: 功能区镀金30U", 锡脚Gold Flash

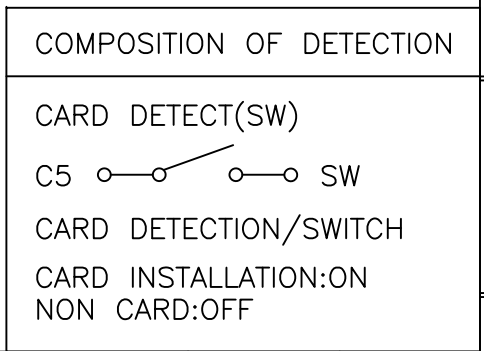
| | | | | | | | | | | | |
|-------------------|----------|---------|----------------|----------|----------------------------|----------|----------------------|--|----|-------|----------|
| GENERAL TOLERANCE | | DWG.NO. | SP135-AN401-00 | PART.NO. | SP135-AN401-** | DRAWN | L. M. J 2019. 05. 07 | UNIT | mm | SCALE | NO SCALE |
| x. ±0.50 | x. *± 5° | REV. | A | TITLE | Nano SIM H1.47-2 with tray | CHECKED | | 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD. | | | |
| .x±0.25 | .x*± 2° | SIZE | A4 | SHEET | 1 OF 3 | APPROVED | | | | | |
| .xx±0.15 | .xx± 1° | A4 | | | | | | | | | |



- NOTE:
- Material:
 - Housing: High Temperature Thermoplastic,(LCP S475)Color Black UL 94V-0
 - Contact: Phosphor Bronze(C5210R-H,T=0.08±0.01mm)
 - Cover: SUS304-H T=0.15±0.03mm
 - Plating:
 - Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - Cover:
 - Underplating: Ni overall 30U" Min.
 - Solder area: Gold 0.80u" Min.
 - Specification:
 - Current Rating: 0.5mA max.
 - Contact Resistance: 50mOhms max.
 - Insulation Resistance: 1000MOhms min./500VDC
 - Dielectric Withstanding Voltage:500 V AC/1minute
 - Operating Temperature:-25°C to +85°C
 - Mating Cycles:5000 Insertions

SIM Card Pin Assignments

| NANO SIM CAED | |
|---------------|-------|
| C1 | Vcc |
| C2 | RST |
| C3 | CLK |
| C5 | GND |
| SW | CD/SW |
| C6 | Vpp |
| C7 | DATA |

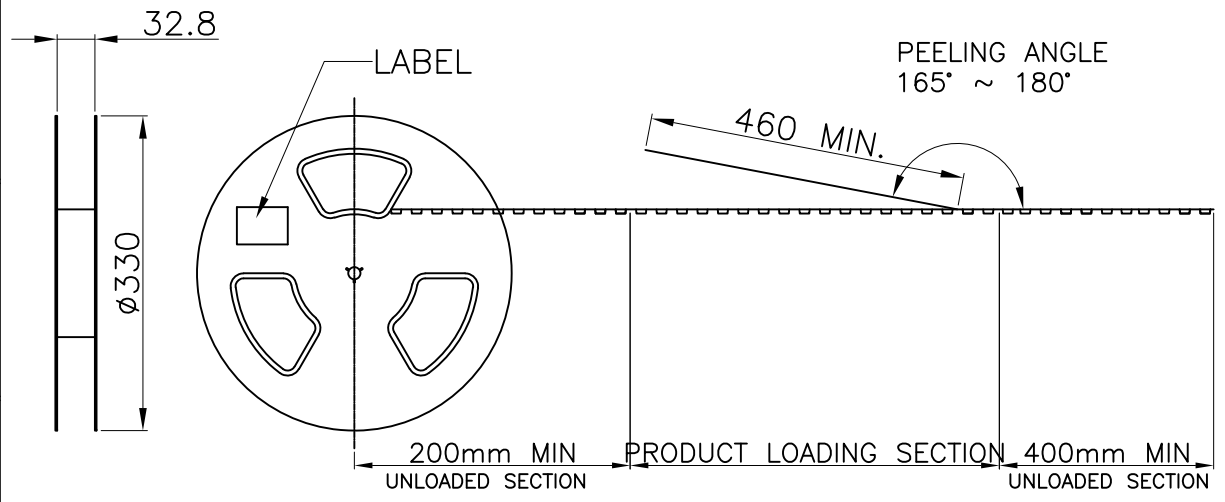


- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA (NO Trace&Via&GND)
- GND PATTERN ONLY

RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

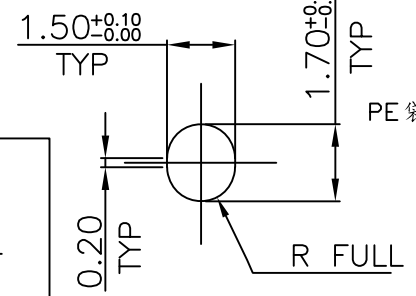
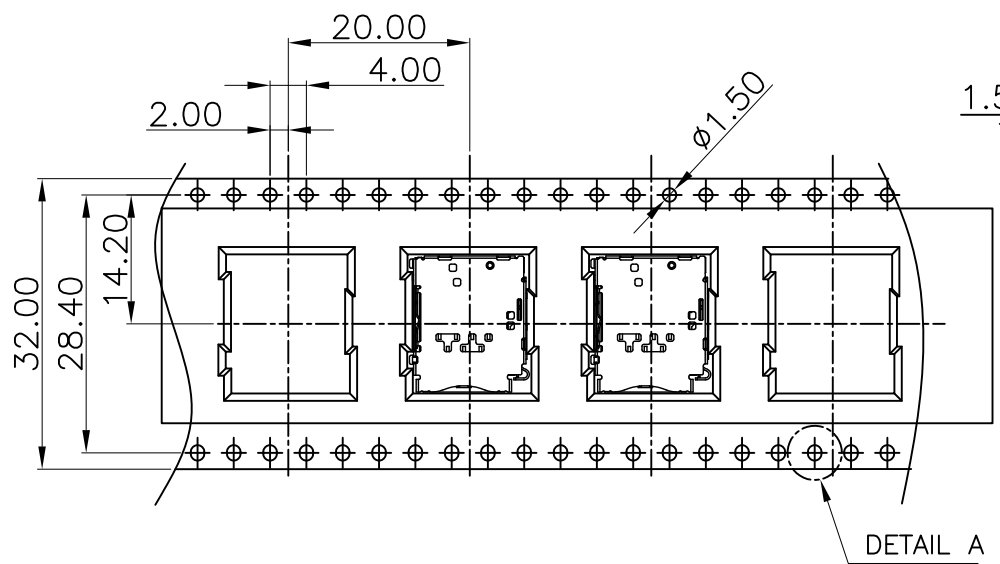
| | | | | | | | | | | | |
|-------------------|----------|---------|----------------|----------|----------------------------|----------|----------------------|--|----|-------|----------|
| GENERAL TOLERANCE | | DWG.NO. | SP135-AN401-00 | PART.NO. | SP135-AN401-** | DRAWN | L. M. J 2019. 05. 07 | UNIT | mm | SCALE | NO SCALE |
| x. ±0.50 | x. *± 5° | REV. | A | TITLE | Nano SIM H1.47-2 with tray | CHECKED | | 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD. | | | |
| .x±0.25 | .x*± 2° | SIZE | | SHEET | 2 OF 3 | APPROVED | | | | | |
| .xx±0.15 | .xx± 1° | A4 | | | | | | | | | |

| | | |
|------|---------|----------------|
| REV. | ECN.NO. | MODIFY.CONTENT |
|------|---------|----------------|

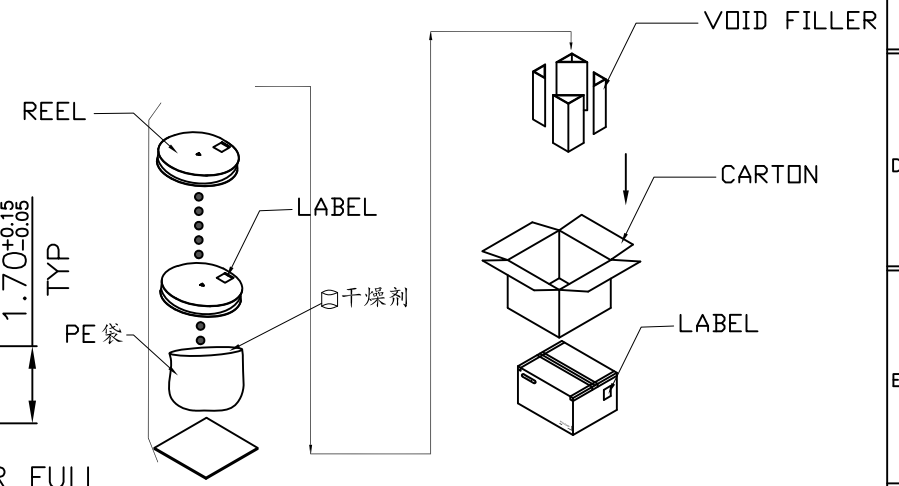


- NOTES :
- MATERIAL :
 COVER TAPE : P.S T=0.05
 CARRIER TAPE : P.S T=0.40
 REEL : PET/PS UL94V-0
 CARTON: CORRUGATED FIBER
 - DIMENSION :
 REEL : SEE DRAWING
 SHIPPING BOX: 350X350X310mm
 - QUANTITY : SEE TABLE
 - PEELING RESISTANCE : 10gf~130gf (for 12~56mm)
 - PEELING SPEED : 300mm/MINUTES

PULL OUT DIRECTION



DETAIL A
SCALE 5:1



| | | |
|----------|----------|------------|
| 1000 | 8 | 8000 |
| PCS/REEL | REEL/BOX | TOTAL Q'TY |

| | | | | | | |
|-------------------|---------|----------------|----------|----------------------------|----------|----------------------|
| GENERAL TOLERANCE | DWG.NO. | SP135-AN401-00 | PART.NO. | SP135-AN401-** | DRAWN | L. M. J 2019. 05. 07 |
| x. ±0.50 | REV. | A | TITLE | Nano SIM H1.47-2 with tray | CHECKED | |
| .x ±0.25 | SIZE | A4 | SHEET | 3 OF 3 | APPROVED | |
| .xx ±0.15 | | | | | | |

OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.